

ABSTRACT

A test apparatus for testing integrated modules has a plurality of connection locations on a carrier substrate. An integrated module may be connected, via a
5 connection location, to a test unit connected to the carrier substrate. The connection locations are arranged in groups within a connection array. A control terminal via which an integrated module may be selected for a test can be provided for each connection location. An address and command terminal can be provided for each connection location. The modules of the number of groups, which are simultaneously operated, are
10 connected to the address and command bus via the respective switching means or switch. The test frequency can thus be increased without adversely affecting the driver load.